Day 0: 1 March 2026, Sunday (Short Courses and Tutorials)			
Venue	**Function Room 8 Ground Mezzanine**	**Function Room 7 Ground Mezzanine**	**Function Room 6 Ground Mezzanine**
08.00 - 08.30	**Registration**		
	Short Course 1: Semiconductor Advanced Manufacturing Technology	**Short Course 2: Semiconductor Design - Modeling: Design Service: Modelling, CAD - Design**	**Short Course 3: Semiconductor Advanced Reliability and Testing**
09.00 - 10.30	**Material Innovations and Process Technology Advances to Enable New Device Architectures for Advanced Nodes Below 3nm** Srinivas Guggilla *Senior Director, Technology Development* Applied Materials	**A Practical Guide to Design-Technology-Co-Optimization** Oskar Baumgartner *COO* Global TCAD Solutions	**Advanced Packaging, Semiconductor and Silicon Photonics Test** Clark Liu *Chief Technical Marketing Officer* Taiwan MJC Co. Ltd
10.30 - 11.00	**Break** @ Ground Mezzanine		
11.00 - 12.30	**Accelerating the AI Era through Heterogeneous Integration** Ashok Muthukumaran *Senior Director* Applied Materials	**Accelerating Semiconductor Innovation with AI-Powered FTCO** Tao Sun *Regional Application Manager* Silvaco	**A First Step in Ensuring Chiplet Reliability** Cher Ming Tan *Professor* Chang Gung University
12.30 - 13.30	**Lunch** @ Ground Mezzanine		
	Tutorial 1: Quantum Computing Technologies	**Tutorial 2: Artificial Intelligence Devices (Edge Computing)**	**Tutorial 3: MEMS / Sensors**
13.30 - 15.00	**Silicon Gate-Defined Quantum Dots for Quantum Computing** Ross Leon *Staff Quantum Engineer* Quantum Motion Technologies	**Artificial Intelligence in Semiconductor Test Engineering with Predictive Defect Capability** Muthuramu Gurusamy *Associate Vice President* Tessolve Semiconductor	**Emerging Technologies and monolithic solutions: CMOS, MEMS & Sensors, Photonics and Hybrid Integration Paradigm Change** Eloi Marigo *Senior Manager,* SilTerra
15.00 - 15.30	**Break** @ Ground Mezzanine		
	Tutorial 4: Memory	**Tutorial 5: Emerging RF Wireless**	**Tutorial 6: 2D Transistors**
15.30 - 17.00	**Spintronic Memristors for Computing** Qiming Shao *Associate Professor* The Hong Kong University of Science and Technology	**Emerging RF Materials for Next Generation Wireless Connectivity Circuits and Devices** Luis Andia *Business Development Director* Soitec Microelectronics	**From Atoms to Circuits: 2D Materials for Logic Scaling and Monolithic 3D Integration** Saptashi Das *Ackley Professor of Engineering and MRI Fellow* The Pennsylvania State University

Day 1: 2 March 2026, Monday (Conference)		
08.00 - 08:30	**Registration**	
08:30 - 09:00	**Opening Ceremony** @ Ballroom 3, Lower Ground Floor	
09:00 - 09:45	**Plenary 1: The Future of Memory Chip Technology and Role of Innovation** Gurtej Sandhu *Principal Fellow and Corporate Vice President*, Micron Technology	
09:45 - 10:30	**Plenary 2: Critical Technologies for Chiplet Integration** Subramaniam Iyer *Distinguished Professor,* University of California, Los Angeles	
10:30 - 10:45	**Advancing Technology Together: Inside IEEE EDS Publications** Renuka P. Jindal *Associate Vice-President, EDS Publications and Products*	
10:45 - 11:00	**Break + Exhibition** @ Grand Foyer, Lower Ground Floor	
11.00 - 11.45	**Keynote 1: AI in Every Layer: Enabling Velocity and Time to Solution** David Fried *Corporate Vice President,* Lam Research	
11.45 - 12.30	**Keynote 2: Powering AI Today and Tomorrow** Chee How Tan *Vice President,* Infineon	
12:30 - 13:30	**Lunch** @ Ballroom 2, Lower Ground Floor **Poster Session 1** @ Grand Foyer, Lower Ground Floor	
13:30 - 15:10	**Technical Parallel Session #1** @ Function Rooms 3 to 12 Lower Ground Floor and Ground Mezzanine Floor	**Industry Panel Session** @ Function Room 1, Lower Ground Floor
15:10 - 15:25	**Break + Exhibition** @ Grand Foyer, Lower Ground Floor	
15:25 - 18:25	**Special Session I: FET100 Forum** @ Ballroom 3, Lower Ground Floor Hiroshi Iwai, *Distinguished Chair Professor*, National Yang Ming Chiao Tung University Dong-Won Kim, *Fellow*, Samsung Electronics Cor Claeys, *Distinguished Professor*, KU Leuven Yue Kuo, *Life Chair Professor*, National Yang Ming Chiao Tung University	
18:25 - 19:30	**Special Session II: Women in Electron Devices / Young Professionals Panel Session** Beth Yam, *Senior Director,* Intel Gauri Karve, *Scientific Director*, IMEC Eu Poh Leng, *Senior Director*, NXP Semiconductors Avinash Kumar, *Chair*, IEEE EDS UKM Student Branch	
19:30 - 21:00	**Welcome Reception** @ Ballroom 4, Lower Ground Floor	

Day 2: 3 March 2026, Tuesday (Conference)		
09.00 - 09:45	**Plenary 3: Manufacturing the Next Era: AI, Remote Operations & the Future of Semiconductor Innovation** Yvonne Keil *Senior Director,* GlobalFoundries	
09:45 - 10:30	**Keynote 3: Traces of Device and Computer Evolution — From Concept to Computer to Artificial Intelligence** Digh Hisamoto *Chief Senior Scientist,* Hitachi Ltd	
10.30 - 10:45	**Break + Exhibition** @ Grand Foyer, Lower Ground Floor	
10.45 - 11.30	**Keynote 4: From Talent to Silicon: Accelerating Malaysia's Sustainable Advanced Semiconductor Ecosystem** Abdul Rahman Mohamed *Vice Chancellor*, Universiti Sains Malaysia	
11.30 - 12.15	**Keynote 5: National Agenda on Bridging Semiconductor and Quantum Technology** Sufian Jusoh *Vice-Chancellor,* Universiti Kebangsaan Malaysia	
12:15 - 12:30	**Building Malaysia's Complete Silicon Ecosystem** Angel Low *General Manager*, ASEM under Malaysia IC Design Park	
12:30 - 13:15	**Lunch** @ Ballroom 2, Lower Ground Floor **Poster Session 2** @ Grand Foyer, Lower Ground Floor	
13:15 - 15:15	**Special Session III: Industry Panel Session**	**13:30 - 16:30** **Ethical AI For Innovation & Decision Confidence** @ Function Room 1, Lower Ground Floor
15:15 - 16:55	**Technical Parallel Session #2** @ Function Rooms 3 to 12 Lower Ground Floor and Ground Mezzanine Floor	
16:55 - 17:10	**Break** @ Lower Ground Floor and Ground Mezzanine Floor	
17:10 - 19:30	**Technical Parallel Session #3** @ Function Rooms 3 to 12 Lower Ground Floor and Ground Mezzanine Floor	**Focus Session: Focus Session: Bio-Hybrid Electronics** @ Function Room 1, Lower Gound Floor
19:30 - 21:30	**Banquet** @ Ballroom 3, Lower Ground Floor	

Day 3: 4 March 2026, Wednesday (Conference)	
08:30 - 09:15	**Plenary 4: Shaping the Next Era of Semiconductor Innovation: From AI-Driven Devices to Advanced Manufacturing** Kazunari Ishimaru *CTO,* Rapidus
09:15 - 10:00	**Plenary 5: Ultra-clean Interfaces in Atomically Thin Materials for Electronics** Manish Chhowalla *Goldsmiths' Professor,* University of Cambridge
10:00 - 10:15	**Defect Localization and Atomic-Scale Root-Cause Analysis by Using Cs-Corrected Electron Optics and Triple Beam System for High-Definition Lamella Preparation** Abby Soo *Technical PA* , Hi-Tech Instruments
10:15 - 10:30	**Break + Exhibition** @ Grand Foyer, Lower Ground Floor
10:30 - 11:15	**Keynote 6: Superconducting Qubit Design and Integration: Relationship to the Semiconductor Industry** Hiu-Yung Wong *Distinguished Professor,* San Jose State University
11:15 - 12:00	**Keynote 7: The Opportunity of 3D Resistive-gate to Replace Floating Gate Memory in the Angstrom Generation** Steve Chung Shao-Shiun *Lifetime Chair Professor* , National Yang Ming Chiao Tung University
12:00 - 12:45	**Keynote 8: Intelligent Infrared Photodetectors** Weida Hu *Vice President,* Shanghai Institute of Technical Physics, Chinese Academy of Sciences
12:45 - 13:45	**Lunch** @ Ballroom 2, Lower Ground Floor **Poster Session 2** @ Grand Foyer, Lower Ground Floor
13:45 - 16:15	**Technical Parallel Session #4** @ Function Rooms 3 to 12 Lower Ground Floor and Ground Mezzanine Floor
16:15 - 16:30	**Break + Exhibition** @ Grand Foyer, Lower Ground Floor
16:30 - 17:00	**Award Presentation and Closing Ceremony** @ Ballroom 3, Lower Ground Floor

Day 4: 5 March 2026, Thursday (Industry Visit)			
	Tour 1: SilTerra + MIMOS Time: 08:00 - 14:30	**Tour 2: ams OSRAM** Time: 08:30 - 12:30	**Tour 3: Inari Amertron** Time: 09:30 - 12:30